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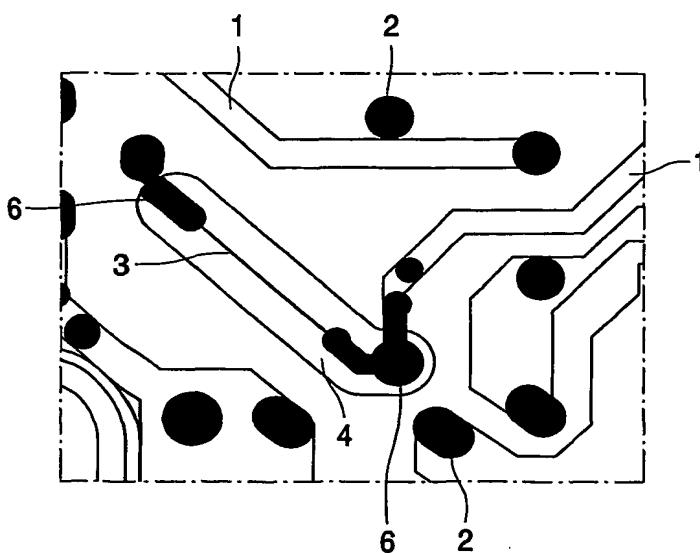
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(54) Title: PRINTED CIRCUIT BOARD INCLUDING A FUSE



(57) Abstract: Printed circuit board comprising a substrate, a plurality of electronic components, and a pattern of metal tracks (1) on said substrate for connecting said electronic components, said metal tracks, typically copper, being covered with a protective layer, typically a solder resist layer, wherein said board further comprises a fuse, said fuse comprising a narrowed metal track (3) within the pattern, wherein said narrowed metal track is uncovered such that it is exposed to air.



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